

IN THE CLAIMS:

Please cancel Claims 1 through 6, 10, and 13 through 24 without prejudice and without dedication or abandonment of the subject matter thereof.

Please amend Claims 7 and 12 and add new Claims 25 through 30 as follows:

7. (Amended) A semiconductor package, comprising:

a substrate;

a die located and supported on said substrate with an adhesive layer between them;

a plurality of signal transferring means which electrically connects said die to said substrate;

a molding compound which seals and protect said die and said plurality of signal transferring means, wherein said molding compound has geometrically a concave at the top surface of the center part ; and

a heat-spreading device which is attached atop said molding compound to conduct heat from said die to ambient air, wherein said head spreading device has a downward bump aligned to said concave; and

a plurality of conductive means attached below said substrate to electrically connect a plurality of conductive traces on said substrate to external circuits.

12. (Amended) The semiconductor package of claim 7, wherein said die has a thermally conductive glue, which conduct heat from said die through

said molding compound to said heat-spreading device.

25. (New) A semiconductor package, at least comprising:

molding means, with a concave located at the central part of the top surface, for sealing and protecting a die, which is adhered on a substrate by an adhesive layer and electrically connected to the substrate by a plurality of signal transferring means; and

heat-spreading means for conducting heat from said die to ambient air by attaching atop said molding means, wherein said heat spreading means has a downward bump aligned to said concave.

26. (New) The semiconductor package of claim 25 further comprises a plurality of conductive means attached below said substrate to electrically connect a plurality of conductive traces on said substrate to external circuits.

27. (New) The semiconductor package of claim 26, wherein said plurality of conductive means includes a plurality of solder balls.

28. (New) The semiconductor package of claim 25, wherein said plurality of signal transferring means can be a plurality of bonding wires.

29. (New) The semiconductor package of claim 25, wherein said heat-spreading means can be made of metal.

30. (New) The semiconductor package of claim 25, wherein said die has